



15. FOR LEAD-FREE PROCESS.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
  - PACKAGING: TAPE & REEL.
  - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
  - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
  - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
  - INSERTION FORCE: 0.4 - 3kg.
  - WITHDRAWAL FORCE: 0.3 - 2kg.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
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REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
A	PDR :109111311A	Bruce	2010.02.04
B	ECN NO.S110320	Swing	2011.03.10

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	SHIELDING	1	PHOSPHOR BRONZE 0.2t	60μ" Ni PLATING MIN.
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120μ" Sn ON SOLDER GOLD FLASH ON CONTACT AREA ALL OVER 50μ" Ni PLATING.
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	300μ" Sn ON CONTACT AREA 120μ" Sn ON SOLDER TAIL AREA ALL OVER 50μ" Ni PLATING. GOLD FLASH ON CONTACT AREA OVER 50μ" Ni PLATING.
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	
B	EARTH	1	COPPER ALLOY 0.2t	Au 30μ" OVER 50μ" Ni PLATING
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X. :±0.5	X :±2°
X.X :±0.3	X.X :±1°
X.XX :±0.2	
X.XXX :±0.1	

Singatron Enterprise Co., Ltd.  
信亨企業股份有限公司

3.5ø PHONE JACK

PART NO. 2S1-S351-060

SCALE:4:1 UNIT: mm

SIZE: A3 SHEET:1 OF 1 REV:B

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